



NOTES.

- 1 PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION
- 2 SEAL AREA TO BE METALLIZED
- 3 DIE ATTACH AREA TO BE METALLIZED
- 4 SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
- 5 LEAD RESISTANCE:  $0.2 \Omega \text{ MAX.}$



上海季丰电子科技有限公司  
GIGA FORCE ELECTRONICS CO., Limited

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